

Remarks

This is intended to be a complete response to the Official Action mailed February 7, 2007, in which claims 1-16, 21, 23-28 and 30 were rejected. Claims 1, 3-8, 13-16, 27 and 28 have been cancelled herein without prejudice in the interest of advancing prosecution of the application. Applicant reserves the right to pursue the cancelled claims in a subsequent patent application.

Rejection under §102(b)

Claim 1 stands rejected under 35 U.S.C. 102(b) as being anticipated by US 4,628,598.

As indicated above, claim 1 has been cancelled without prejudice, thereby mooting the rejection.

Rejection under §103(a)

Claims 3-8, 13-16, 27 and 28 stand rejected under 35 U.S.C. 103(a) as being unpatentable over US 5,191,174 (Chang) in view of US 5,342,999 (Frei).

As indicated above, claims 3-8, 13-16, 27, and 28 have been cancelled without prejudice, thereby mooting the rejection.

Rejection under §102(e)

Claims 2, 9-12, 21, 23-26, and 30 stand rejected under 35 U.S.C. 102(e) as being anticipated by US 5,677,515 (Selk).

The rejection is respectfully traversed.

In the rejection it is stated:

"Selk discloses, referring primarily to figures 3a and 3b, a printed circuit board having an EMI shielding structure for shielding wiring circuit traces on a plurality of circuit trace layers applied on a plurality of printed circuit board layers and electrically isolated there between by the printed circuit board layers and having a printed circuit board multi-layer structure, characterized by: a trench (72, 74) having a rim about an opening of the trench at a top printed circuit board layer and said trench extending through a plurality of printed circuit board layers to a grounding plane (50) exposing said grounding plane and said trench having an interior wall with a conductive plating material (70) applied over said interior wall and said trench having a length greater than two times a breadth of said trench and wherein the trench completely surrounds an area and extends adjacent to the perimeter of the printed circuit board (see figure 3b) and wherein said conductive plating material electrically connects to said exposed grounding plane [claim 2]. (emphasis added)," and,

"Additionally, Selk discloses, a printed circuit board having a reference plane structure for fixing a potential reference for a plurality of wiring circuit trace layers that are electrically isolated there between by a plurality of printed circuit board layers and having a printed circuit board layer with a main surface, characterized by: a wire trace circuit layer (44) applied to said main surface; a printed circuit board insulation layer (62) formed over said wire trace circuit layer; a reference plane (50) applied over the printed circuit board insulation layer; a trench (72, 74) having an interior wall extending through and exposing the wire trace circuit layer, and the trench further extending through the insulation layer to the reference plane wherein the reference plane is exposed and wherein the trench completely surrounds an area and extends adjacent to the perimeter of the printed circuit board

layer (col. 4, lines 50-55); and a conductive plating layer (70) on the interior wall electrically connects the wire trace circuit layer to the reference plane [claim 9], wherein the trench completely encompasses the wire trace circuit layer [claim 10], wherein the reference plane is fixed at a ground potential (see col. 4, lines 55-65) [claim 11], wherein the reference plane is fixed at a reference voltage (see col. 4, lines 55-65) [claim 12].”

However, as shown in Attachment 1 submitted herewith, first and second grooves 72' and 74' of Fig. 3b do not completely surround the signal layer 42. As indicated presently in Attachment 1, the first and second grooves 72' and 74' extend completely to the edge of the wiring board 40. Gaps at the right hand edge of the board, represented by added reference letters A and B, indicate portions of the wiring board 40 which are not surrounded by the grooves, thus the signal layer 42 is not completely surrounded by the first and second grooves 72' and 74'; contrary to the present claims.

Selk thus does not teach each and every element of the claimed invention as required under 35 U.S.C. §102.

In view of the above, applicant respectfully requests reconsideration and withdrawal of the rejection under §102.

CONCLUSION

In view of the above, applicant respectfully submits the claims are now in a condition for allowance and requests issuance of a Notice of Allowance.

Respectfully submitted,

A handwritten signature in black ink, appearing to read 'Christopher W. Corbett', written over a horizontal line.

Christopher W. Corbett

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